



US00D518003S

(12) **United States Design Patent**
Hahn et al.

(10) **Patent No.:** **US D518,003 S**
(45) **Date of Patent:** **** Mar. 28, 2006**

(54) **HOUSING FOR AN ELECTRONIC CIRCUIT MODULE**

6,628,521 B1 * 9/2003 Gustine et al. 361/704
6,649,830 B1 * 11/2003 Bartlett et al. 174/50

(75) Inventors: **Amand J. Hahn**, Lansdale, PA (US);
Rod P. Boer, Hartboro, PA (US); **Eric A. Schneider**, Erdenheim, PA (US)

* cited by examiner

Primary Examiner—Prabhakar Deshmukh

Assistant Examiner—Selina Sikder

(73) Assignee: **Honeywell International Inc.**,
Morristown, NJ (US)

(74) *Attorney, Agent, or Firm*—Anthony Miologos

(**) Term: **14 Years**

(57) **CLAIM**

The ornamental design for a housing for an electronic circuit module, as shown and described.

(21) Appl. No.: **29/232,728**

DESCRIPTION

(22) Filed: **Jun. 22, 2005**

The housing for an electronic circuit module is intended to be used to house electronic circuit board and their included electronic components and other electronic circuitry.

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/184**

(58) **Field of Classification Search** D13/184;
D14/240; 174/50, 52.1; 220/4.02; 361/600,
361/601, 679, 688, 704, 724, 796
See application file for complete search history.

FIG. 1 is a right side perspective view of the housing for an electronic circuit module embodying our new design; FIG. 2 is a left side elevational view thereof; FIG. 3 is a right side elevational view thereof; FIG. 4 is a top plan view thereof; and, FIG. 5 is a bottom plan view thereof.

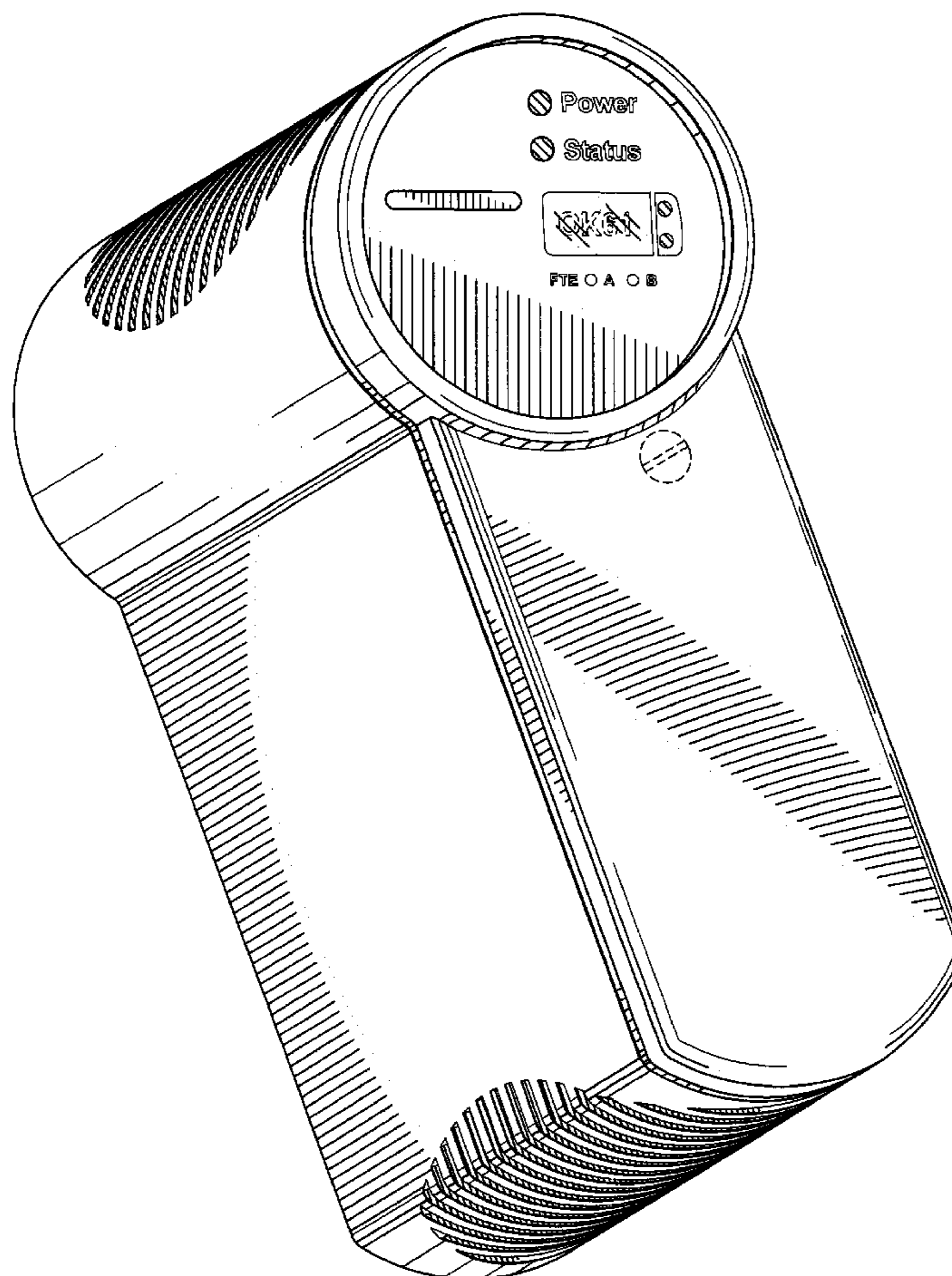
The broken line disclosures in the drawings are for illustrative purposes only and form no part of the claimed design.

(56) **References Cited**

U.S. PATENT DOCUMENTS

5,842,514 A * 12/1998 Zapach et al. 165/104.33
6,625,017 B1 * 9/2003 Lin et al. 361/690

1 Claim, 5 Drawing Sheets



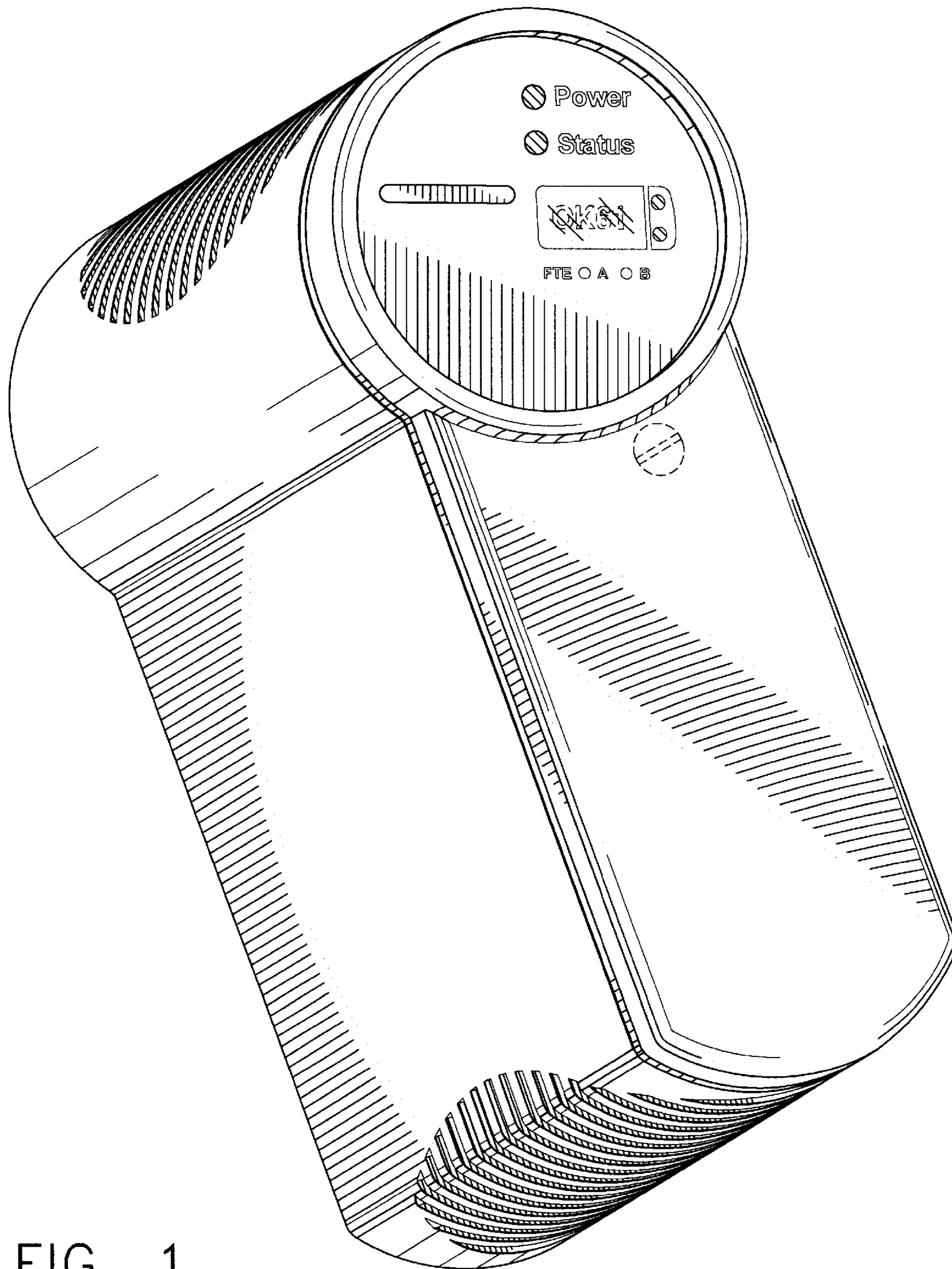


FIG. 1

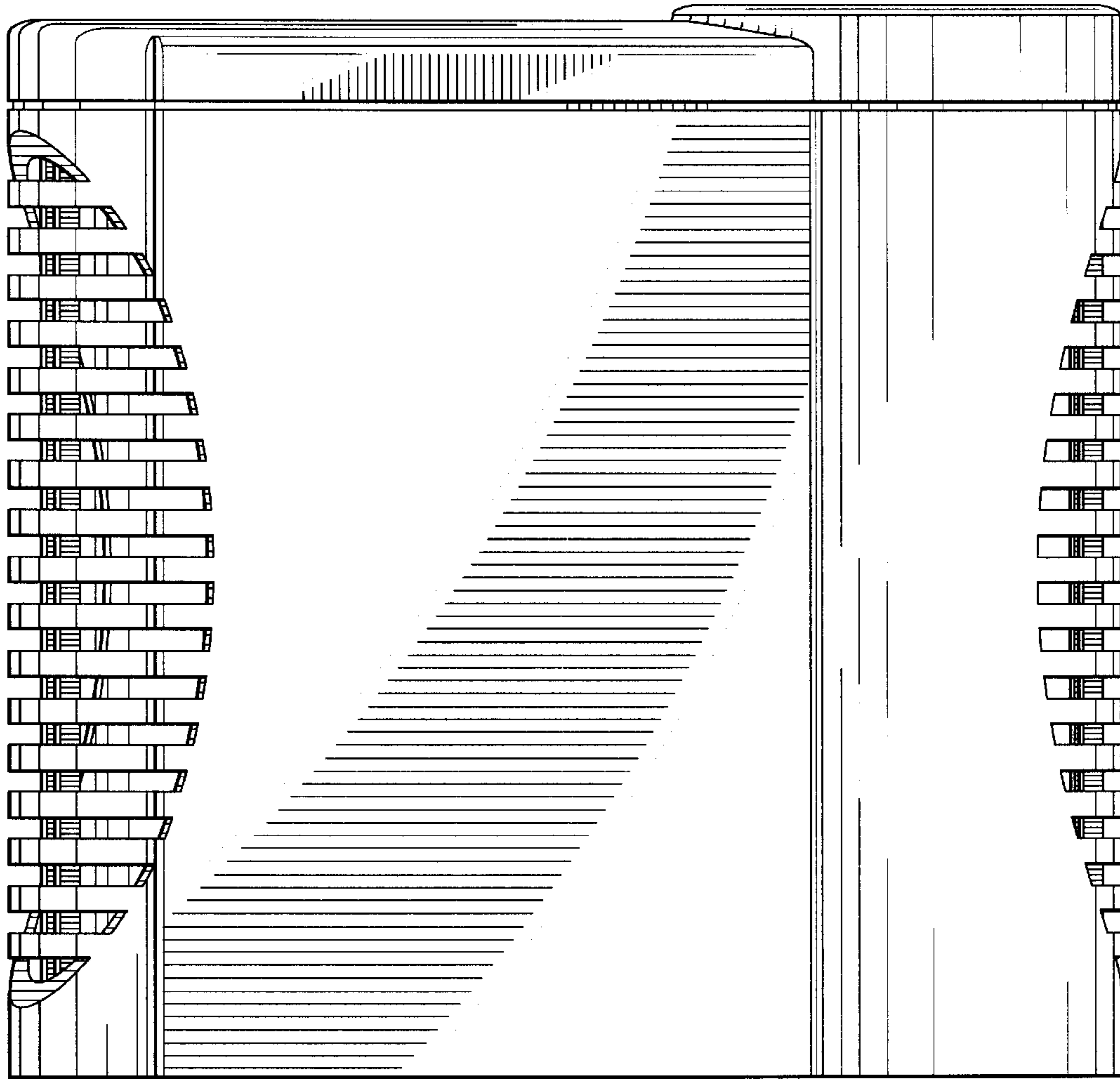


FIG. 2

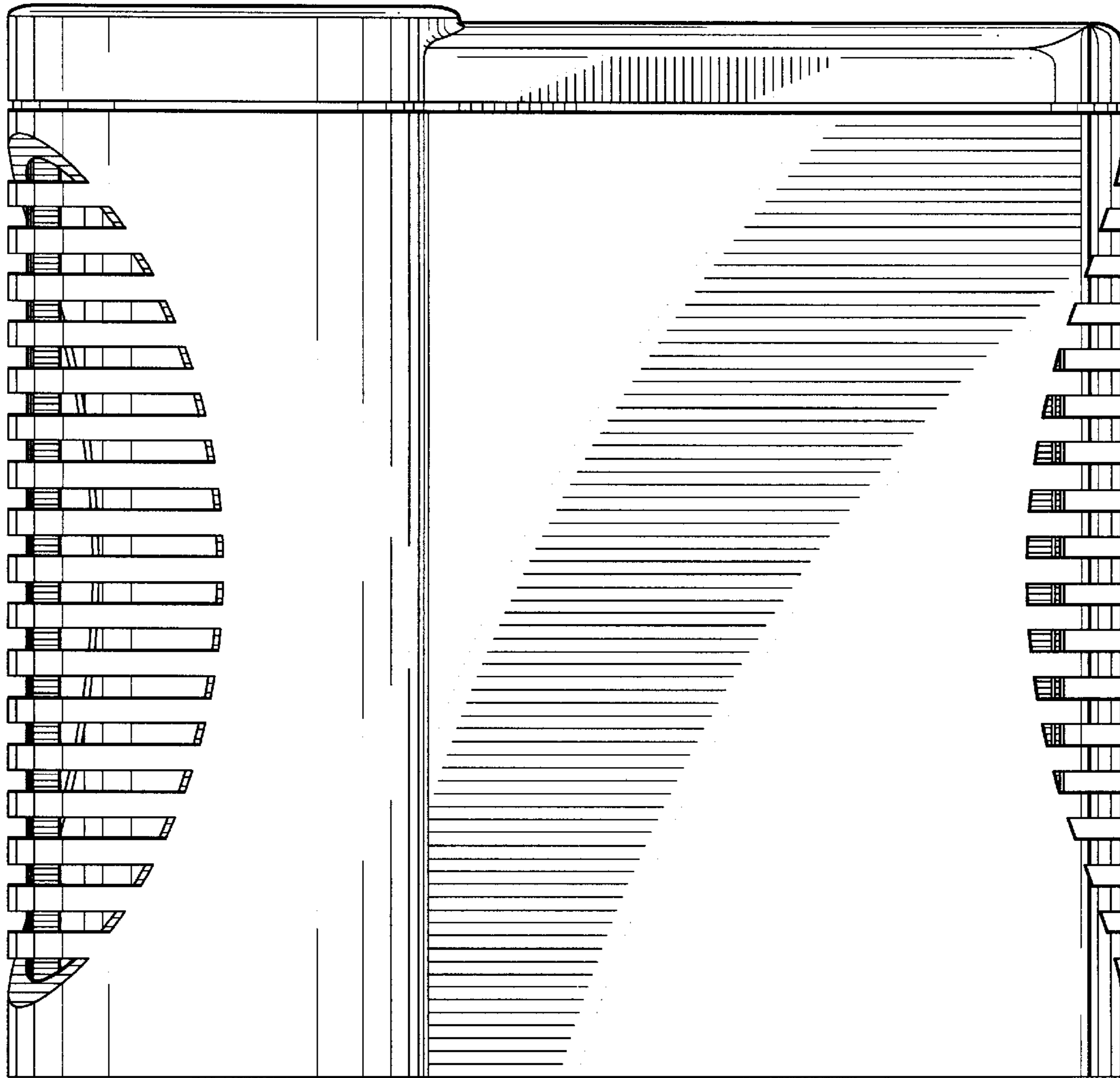


FIG. 3

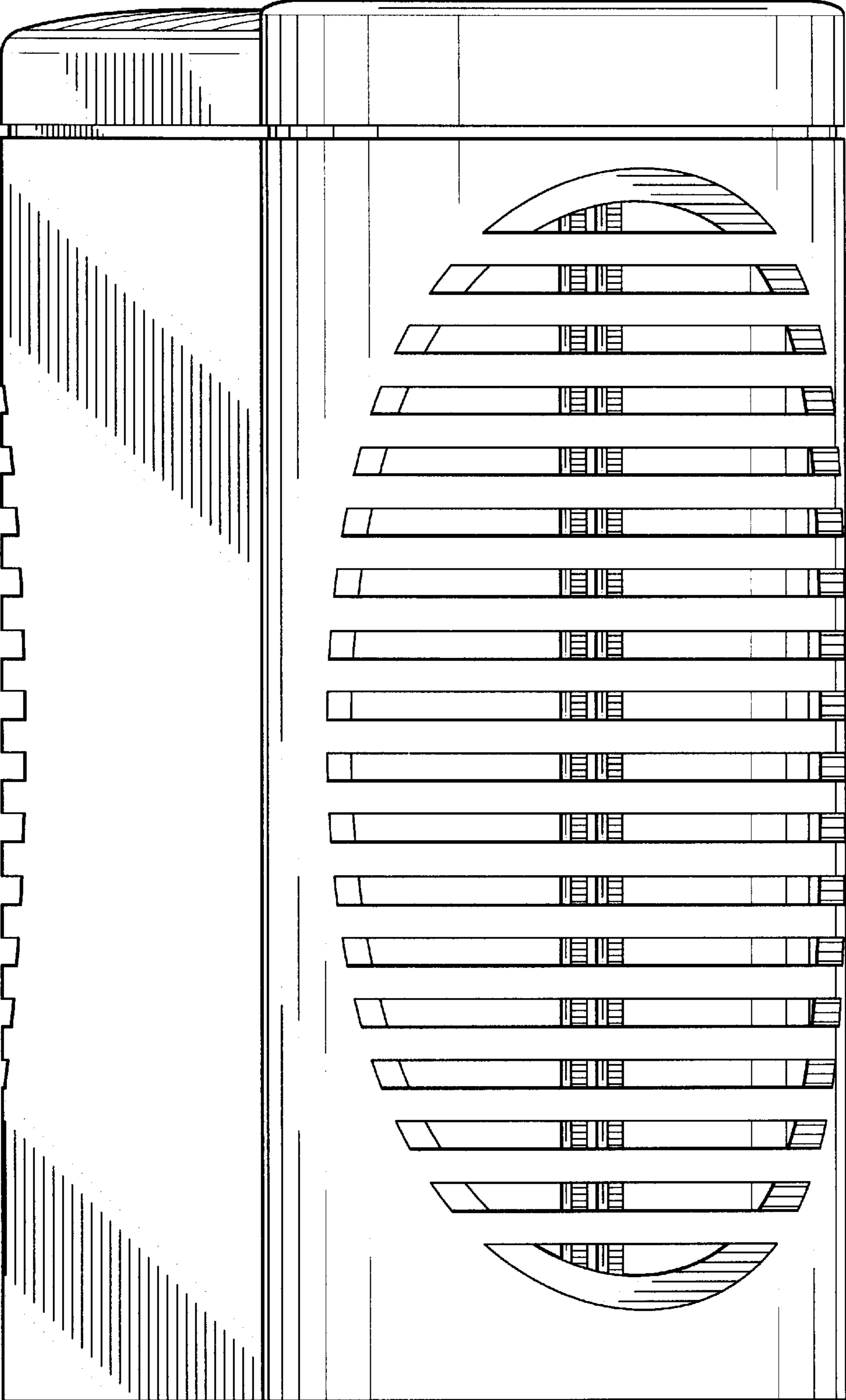


FIG. 4

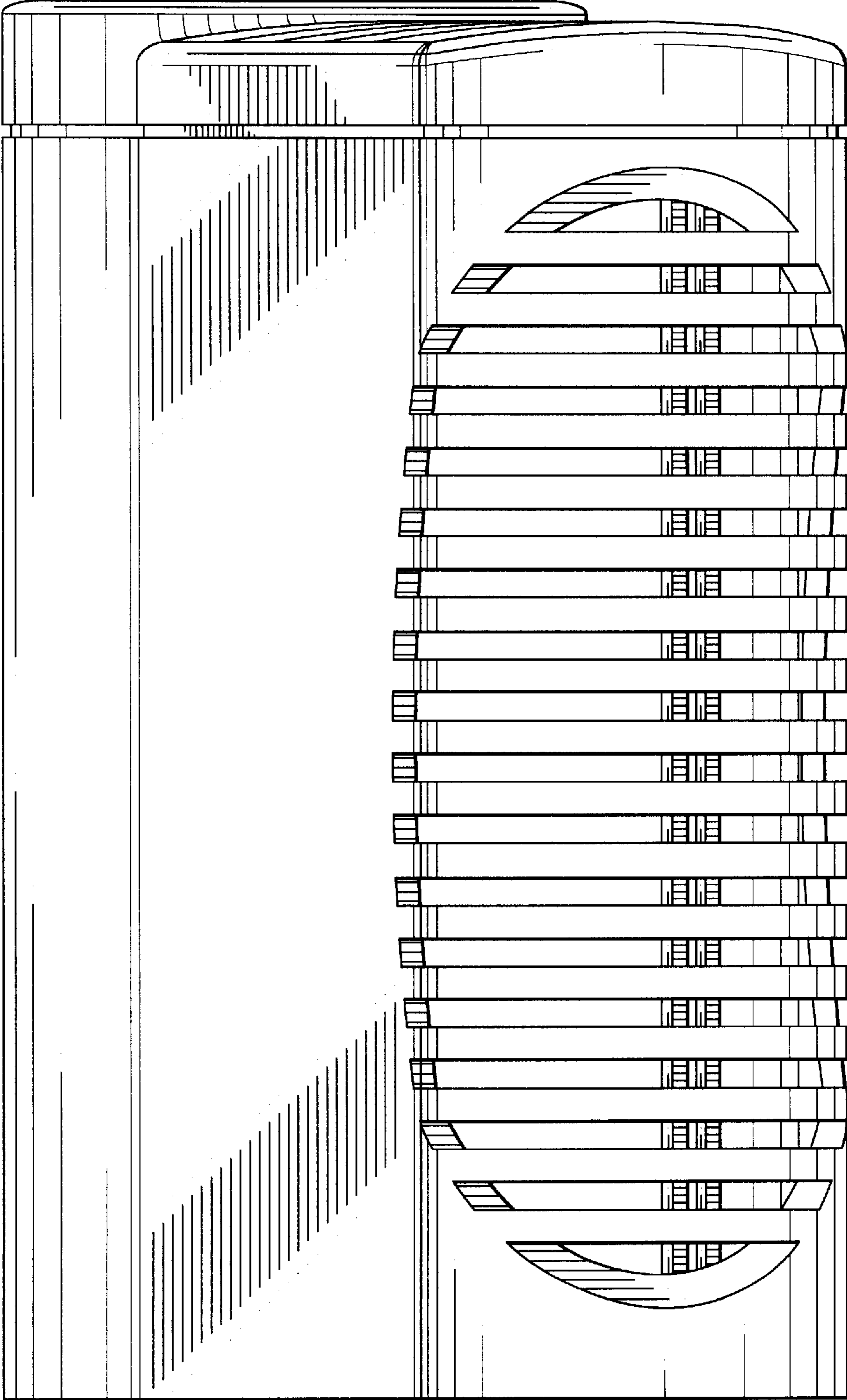


FIG. 5